PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Robert H. DENNARD	05/06/2008
Mark C. HAKEY	05/02/2008
David V. HORAK	05/02/2008
Sanjay MEHTA	05/02/2008

RECEIVING PARTY DATA

Name:	INTERNATIONAL BUSINESS MACHINES CORPORATION
Street Address:	New Orchard Road
City:	Armonk
State/Country:	NEW YORK
Postal Code:	10504

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12115690

CH $40.00 12115690

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	BUR920080076US1
NAME OF SUBMITTER:	Andrew M. Calderon

Total Attachments: 3
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DOCKET NO. BUR920080076US1

ASSIGNMENT

INVENTOR
AND CITY

Whereas, we

(1) **Robert H. DENNARD**
County of Westchester
of Croton-on-Hudson,
and State of New York,

and (2) **Mark C. HAKEY**
County of Franklin
of Fairfax,
and State of Vermont,

and (3) **David V. HORAK**
County of Chittenden
of Essex Junction,
and State of Vermont,

and (4) **Sanjay MEHTA**
County of Schenectady
of Niskayuna,
and State of New York,

have invented certain improvements in **METHOD FOR FABRICATING SEMICONDUCTOR DEVICE HAVING CONDUCTIVE LINER FOR RAD HARD TOTAL DOSE IMMUNITY**

DATES THAT
INVENTORS
SIGNED THE
DECLARATION

and executed, respectively, a United States patent application therefore on

(1) May 6, 2008, (2) ______________, 2008,
(3) ______________, 2008, (4) ______________, 2008,

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and in all foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed and sealed:

(1) Robert H Dennard
Robert H. DENNARD
on May 6, 2008

(2) ______________________________
Mark C. HAKEY
on ______________, 2008

DOCKET NO. BUR920080076US1

ASSIGNMENT

Whereas, we

INVENTOR AND CITY	(1) **Robert H. DENNARD** County of Westchester	of Croton-on-Hudson, and State of New York,
	and (2) **Mark C. HAKEY** County of Franklin	of Fairfax, and State of Vermont,
	and (3) **David V. HORAK** County of Chittenden	of Essex Junction, and State of Vermont,
	and (4) **Sanjay MEHTA** County of Schenectady	of Niskayuna, and State of New York,

have invented certain improvements in **METHOD FOR FABRICATING SEMICONDUCTOR DEVICE HAVING CONDUCTIVE LINER FOR RAD HARD TOTAL DOSE IMMUNITY**

DATES THAT INVENTORS SIGNED THE DECLARATION

and executed, respectively, a United States patent application therefore on

(1) __________, 2008, (2) 5/22, 2008,

(3) 5/2, 2008, (4) __________, 2008,

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and in all foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed and sealed:

(1) ____________________ on __________, 2008
Robert H. DENNARD

(2) Mark C. Hakey on 5/2/, 2008
Mark C. HAKEY

(3) ______________________ on 5/2/08, 2008
David V. HORAK

(4) DCMehta on May 2, , 2008
Sanjay MEHTA